

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT3162999

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
DONG WON LEE	12/15/2014
RECEIVING PARTY DATA	
Name:	SOLID, INC.
Street Address:	SPACE 8TH FL., 220 PANGYOYEOK-RO, BUNDANG-GU, SEONGNAM-SI
City:	GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF
Postal Code:	463-400
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14411483
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	P54714ZN11
NAME OF SUBMITTER:	JONG H PARK
SIGNATURE:	/JONG H PARK/
DATE SIGNED:	12/26/2014
Total Attachments: 1	
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ASSIGNMENT

AS A BELOW NAMED INVENTOR, I, and each of us, individually hereby declare that:
IN CONSIDERATION of the sum of TEN (\$10.00) dollars or the equivalent thereof, and other good and valuable consideration, the receipt of which from the hereinafter named Assignee is hereby acknowledged, I do hereby sell, assign and forever grant and convey unto:

SOLID, INC.

having a place of business at Space 8th Fl., 220 Pangyoyeok-Ro, Bundang-Gu, Seongnam-Si, Gyeonggi-Do 463-400, Republic of Korea

Who is my Assignee, and to the successors and assigns of my Assignee, all my right, title and interest, in and for the United States of America and all other countries, including all rights of priority, in and to the invention entitled:


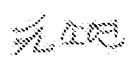
Communication Module Assembly

invented by me and described in an application for a United States patent the specification of which is either attached hereto or otherwise accompanies this Assignment and in and to all United States patents which may be granted thereon and therefore, and in and to all certificates of corrections, divisions, continuations, continuations-in-part, reissued and re-examined patents, and to any extensions thereof, said interest being the entire ownership of the patent when granted, to be held and enjoyed by said **SOLID, INC.**, my Assignee, its successors, assigns or other legal representatives, to the full end of the term, terms, or any extension or renewal thereof, for which said patent or patents may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment, sale and conveyance had not been made;

AND I hereby covenant and agree to sign and execute, without receiving any money or other consideration, any further documents or instruments which may from time-to-time be either necessary, lawful, proper or requested by the Assignee, in the prosecution of the above-named application or in the preparation and prosecution of all substitute applications, certificate of correction, division, continuation, continuation-in-part, reissue, re-examination, in any amendment, extension, or interference proceeding, whether administrative or judicial, or otherwise, to secure the title hereto in said Assignee, together with the right of priority under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreement or treaty to which the United States of America adheres.

I hereby authorize and request the Patent Office Officials in the United States and its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said my Assignee.

IN WITNESS WHEREOF, I have set our hands and seals on the dates written beside my name:

Legal Name of First Inventor: LEE, Dong Won	
Inventor's Signature: 	Date: 2014. 12. 15
Legal Name of Additional Inventor: WON, So Yeon	
Inventor's Signature: 	Date: 2014. 12. 15

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